

肥特補科技  
Feedpool Technology  
Co., Ltd.



Fast UV cure, thermal post-cure



Strong adhesion to various substrates

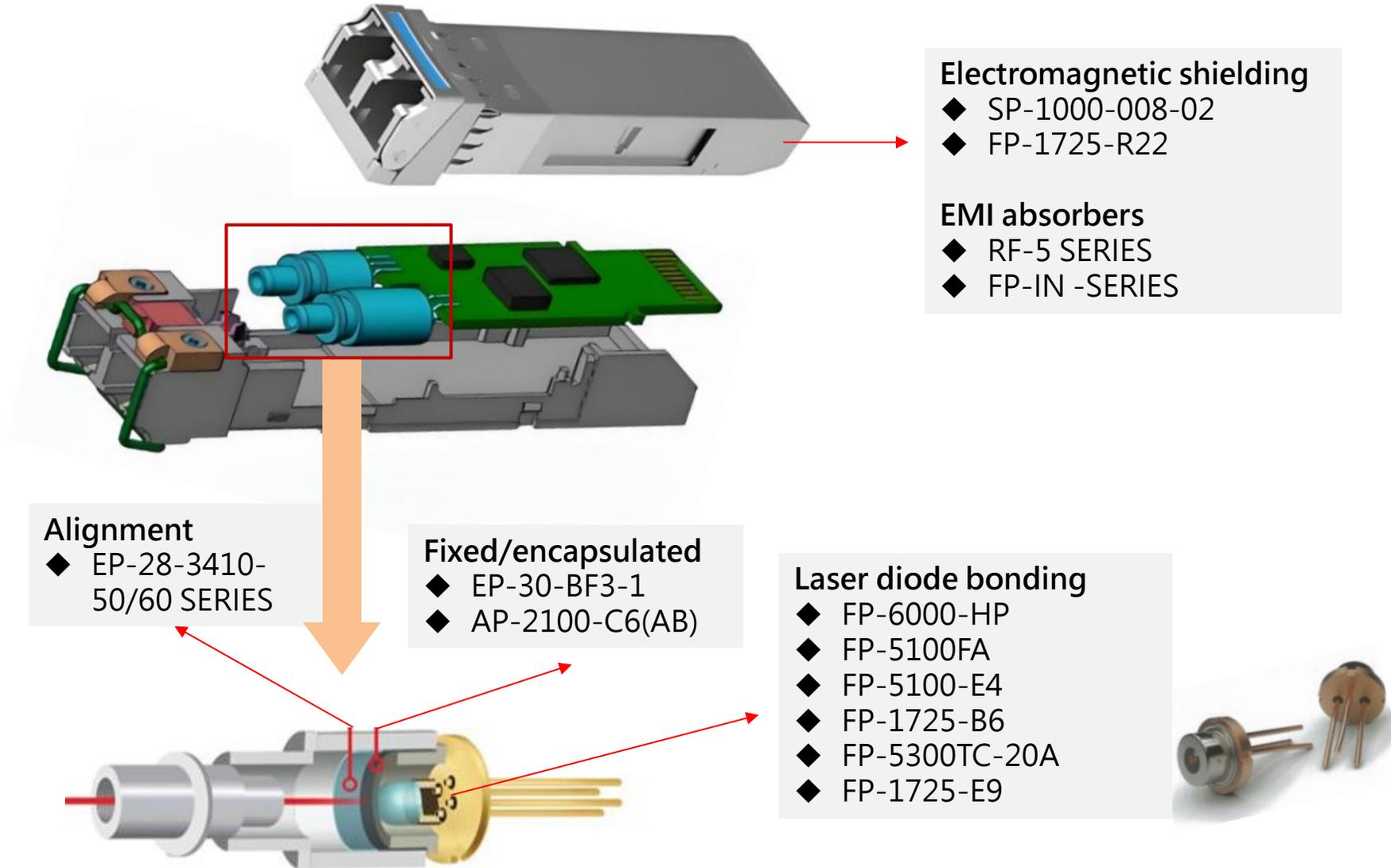


Low CTE, high dimensional stability

**UV-Thermal Dual-Cure  
Insulating Adhesive**

**EP-28-3410-60M**

# Optical Module Product Applications





As the optical industry scales, the demand for massive data transmission has driven module power levels higher. To address these thermal challenges, Feedpool has developed a high-performance **UV/Thermal Dual-Cure adhesive**.

The **EP-28-3410-60M** offers the following key advantages:

- ❑ **Rapid UV Curing:** Enables instant positioning and bonding of precision components.
- ❑ **Low CTE:** Ensures dimensional stability under thermal variations; ideal for alignment and fixation of precision optical components.
- ❑ **Broad Adhesion:** Reliable bonding to Glass, Metal, PEI, PCB, Ceramic, Gold-coated, Aluminum, and FeNi alloys.
- ❑ **Environmental Resistance:** Excellent thermal conductivity and sealing; provides waterproof protection and thermal shock resistance.
- ❑ **Primary Application:** Optical modules.



### Physical Properties

Appearance	Milky White
Density	1.82 g/cm <sup>3</sup>
Viscosity @ 25°C	80000 cp
TI @ 25°C	1.18
Work Life @ 25°C	24 hrs
Storage Life @ -20 ~ -40°C	6 months

### Curing Condition

UV curing	High Pressure Hg Lamp(200~500nm) or UV LED (365nm) 2000~4000 mJ/cm <sup>2</sup>
Thermal curing	70°C@90 mins or 85°C@75 mins or 100°C@60 mins
Cured Properties	
Hardness	Shore D 92
Tg	125 °C
CTE < Tg( $\alpha$ 1)	16 ppm/°C
CTE > Tg( $\alpha$ 2)	61 ppm/°C
Modulus @25°C	10300 MPa

# Comparison of Physical Properties



	OPTOCAST 3410 VM	EP-28-3410-60M
Appearance	Milky White	Milky White
Density (g/cm <sup>3</sup> )	1.85	1.82
Viscosity@25°C (cp)	60000	80000
TI @25°C	1.22	1.18
Filler Content (%)	78.5	75.5
Hardness (ShoreD)	92	92
CTE (ppm/°C)	12 / 39	16 / 61
Tg (°C)	169	125
Modulus (MPa)	13615	10300

# Comparison of Curing Condition



	OPTOCAST 3410 VM	EP-28-3410-60M
UV Curing	320 ~ 550nm	320 ~ 550nm or UVLED(365nm) 2000 ~ 4000 mJ/cm <sup>2</sup>
Thermal Curing	110 ~130°C @10~30min (No Low Temperature Curing)	70°C@90 mins or 85°C@75 mins or 100°C@60 mins

# Adhesion Comparison with Commercial Products



Cured Properties		OPTOCAST 3410 VM	EP-28-3410-60M	FeedPool Test Method
Substrate	PEI	○	○	Post Curing Evaluation
	FeNi alloy	○	○	
	Al	○	○	
	FPC /PCB	○	○	
	Gold-coated	○	○	
	Glass	○	○	



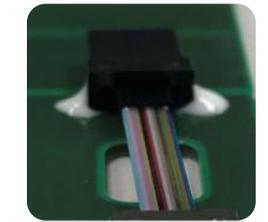
PEI



FeNi alloy



Al



FPC/PCB

Reliability TCT (-40°C/30mins~120°C/30mins · 10 cycles)				
Substrate	PEI	○	○	Post Curing Evaluation
	FeNi alloy	○	○	
	Al	○	○	
	FPC /PCB	○	○	
	Gold-coated	○	○	
	Glass	○	○	



Gold-coated

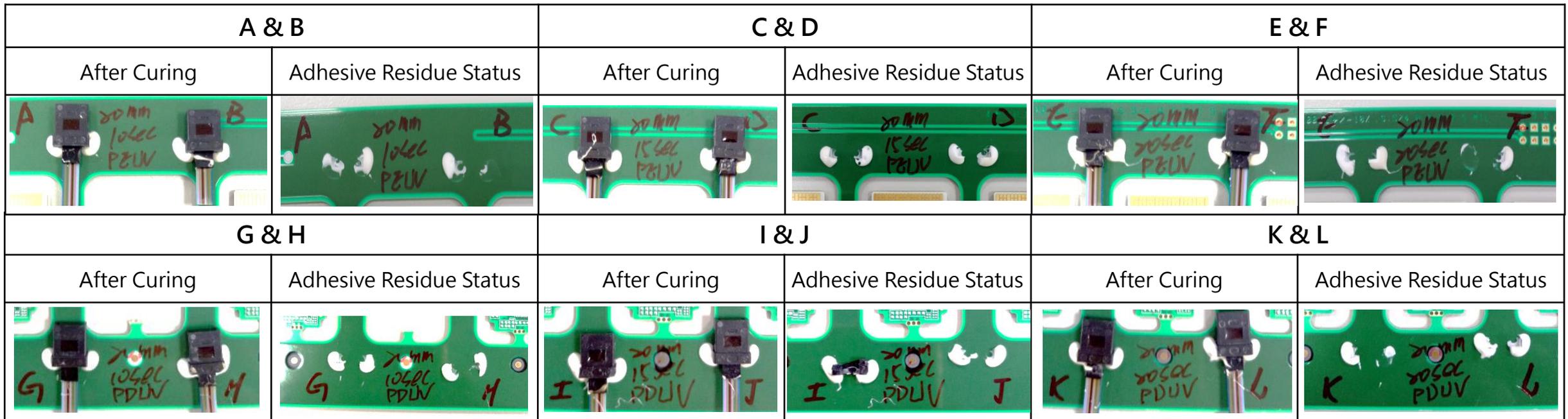


Glass



Sample SN	A	B	C	D	E	F	G	H	I	J	K	L
Setting	Dispensing Time 5s · Pressure 6kg/cm <sup>2</sup>											
Height of UV Light	20mm											
Power of UV Light(mW)	500	500	500	500	500	500	311	311	311	311	311	311
Curing Time(sec.)	10	10	15	15	20	20	10	10	15	15	20	20
Intensity of UV Light( mJ/ cm <sup>2</sup> )	5000	5000	7500	7500	10000	10000	3110	3110	4665	4665	6220	6220
Curing Condition	70°C-90 min											
Shear Strength(kgf)	8.07	9.16	9.65	9.66	9.64	9.54	9.64	9.64	9.64	9.65	9.65	9.64
Adhesive Interior	Cured	Cured	Cured	Cured	Cured	Cured	Cured	Cured	Cured	Cured	Cured	Cured
Appearance	White	White	White	White	White	White	White	White	White	White	White	White

Curing Condition  
 3000~10000 mJ/cm<sup>2</sup> + 70°C 90min  
 Shear strength >8kgf · and adhesive  
 residue on PCB.



# TCT Reliability



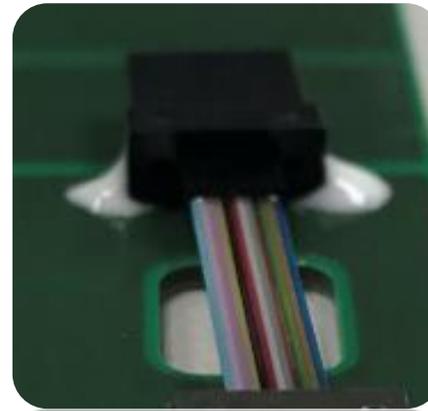
TCT Reliability Test		FeedBond® EP-28-60M					FeedPool Test Method
		Initial	24 cycles	48 cycles	72 cycles	100 cycles	
Substrate	PEI	No cracking or peeling	Post Curing Evaluation				
	FPC /PCB	No cracking or peeling					
	Gold-coated	No cracking or peeling					

TCT Condition: -40°C/30mins~120°C/30mins (1cycle)

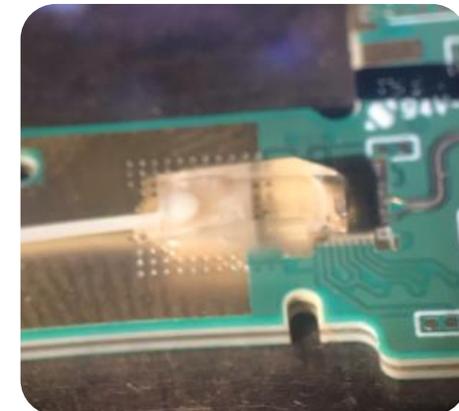
The above data are laboratory results provided for reference only. Customers should conduct thorough testing based on their specific application conditions.



PEI



FPC/PCB



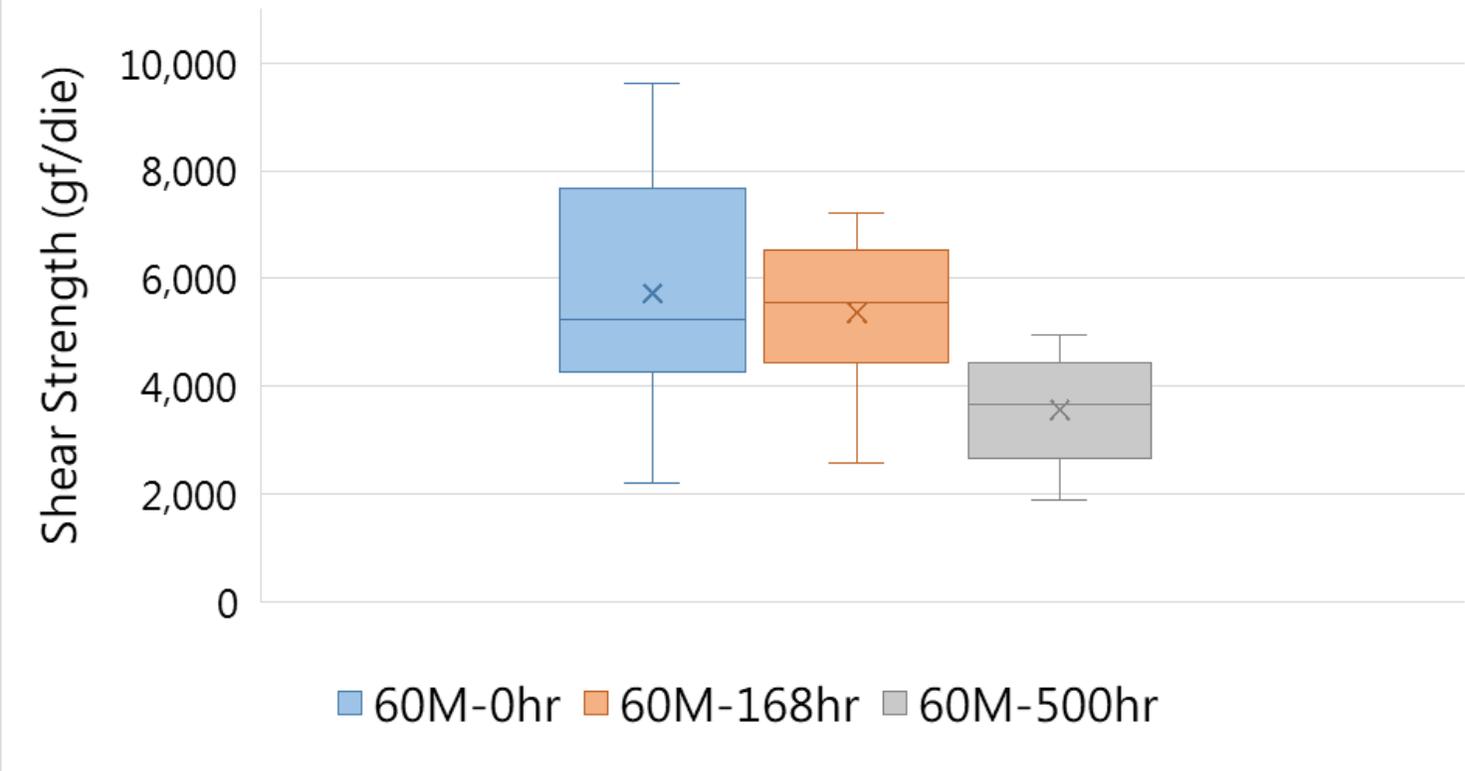
Gold-coated

EP-28-3410-60M has no peeling or cracking after TCT /100cycles

# 85°C/85%RH Reliability Test



### 85°C/85%RH-500hr Reliability Test



Curing Condition: 3000mJ/cm<sup>2</sup> + 100°C-1hr

Adherends: 1mm\*1mm Si die / glass

# Adhesion on Various Substrates and TCT Reliability



Cured Properties		OPTOCAST 3410 GEN2	FeedBond® EP-28-3410-50K	FeedBond® EP-28-3410-60M	FeedPool Test Method
Substrate	PEI	○	○	○	Post Curing Evaluation
	FeNi alloy	○	○	○	
	Al	○	○	○	
	FPC /PCB	○	○	○	
	Gold-coated	○	○	○	
	Glass	○	○	○	

Reliability TCT (-40°C/30mins~120°C/30mins, 10 cycles)					
Substrate	PEI	○	○	○	Post Curing Evaluation
	FeNi alloy	○	○	○	
	Al	○	○	○	
	FPC /PCB	○	○	○	
	Gold-coated	○	○	○	
	Glass	○	○	○	

The data above are measured under laboratory conditions and are for reference only. Customers are advised to conduct thorough testing under their specific application conditions to ensure accuracy



Al



PEI



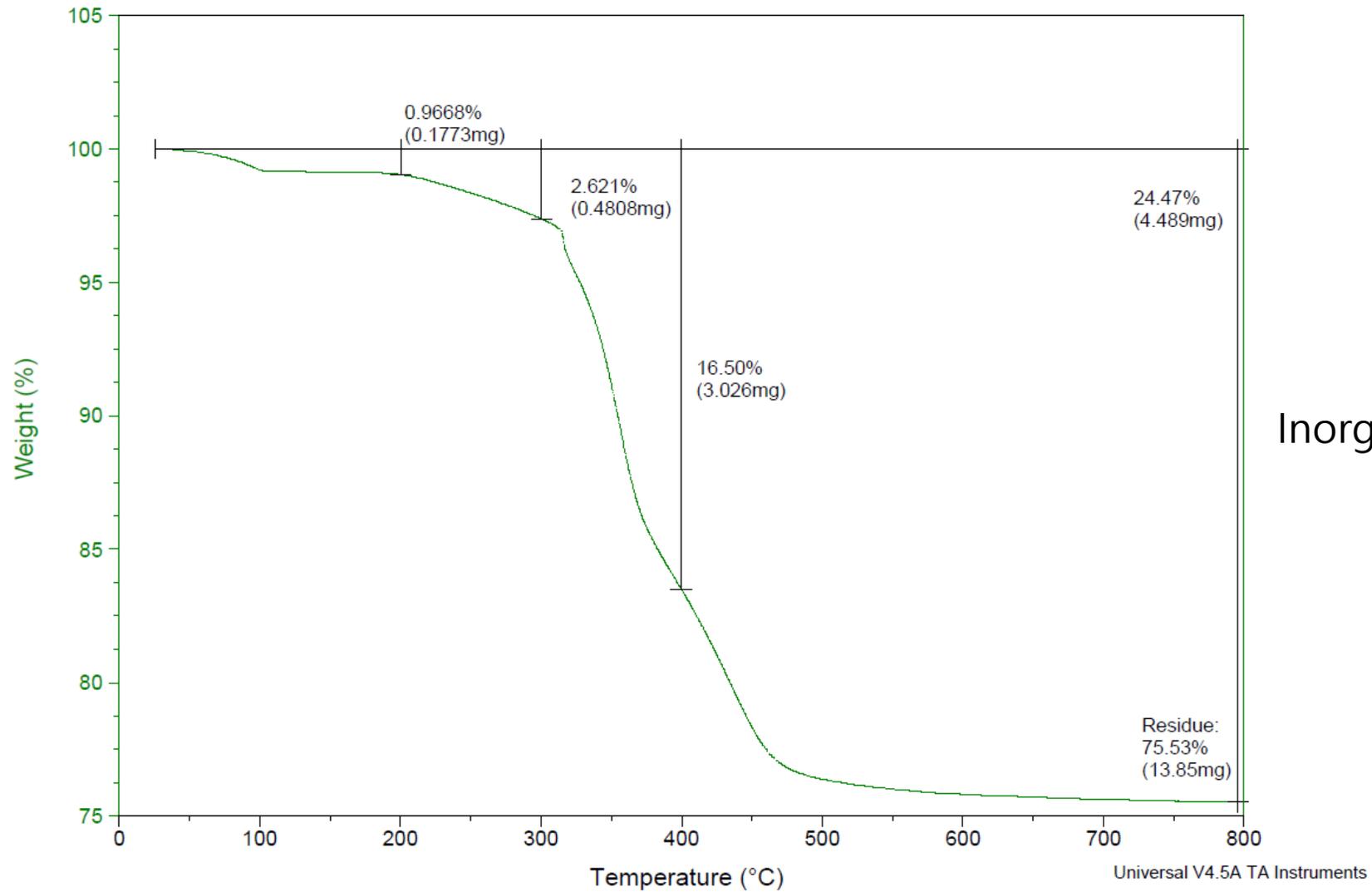
FPC



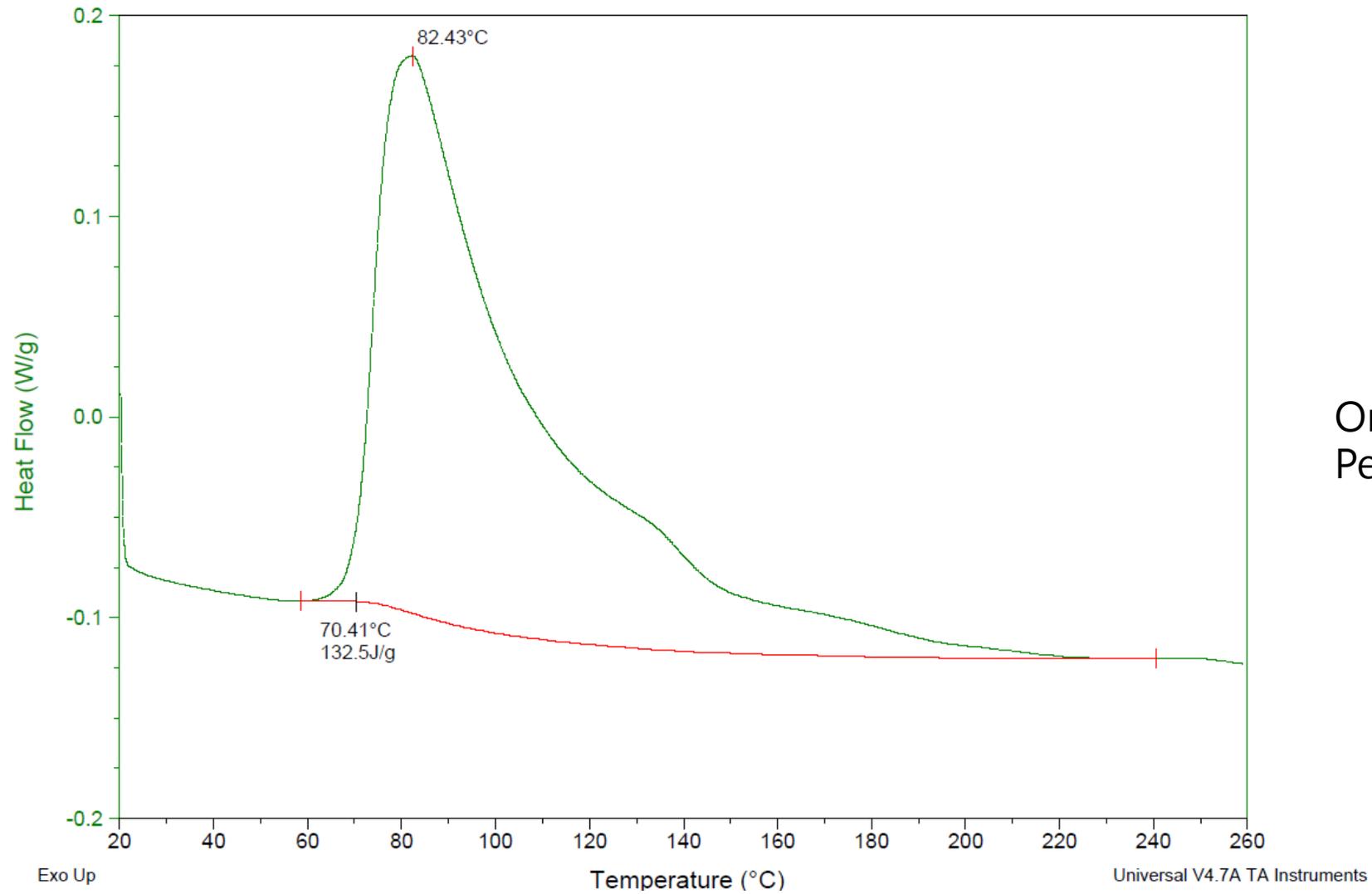
FeNi alloy



Glass



Inorganic Substance Content 75.53%



Onset of Exotherm 70.41°C  
Peak Exotherm 82.43°C

如需進一步資訊，歡迎與我們聯繫：  
For more information, please feel free to  
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